



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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GM1JV35200AE Series GM1BC35370AC GM1GC35200AC GM1EG35200A

Chip LED

1608 size
Thin 0.35 mm thickness

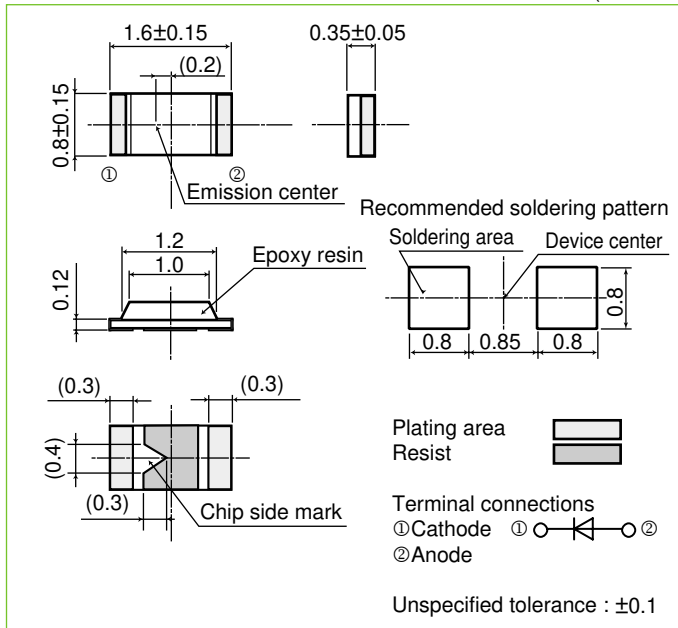


Features

- 0.35 mm thickness thin package
- Outline dimensions : 1.6×0.8×0.35 mm
- Taped products (6 000 pcs/reel)
- Lead-free (product contains no lead)

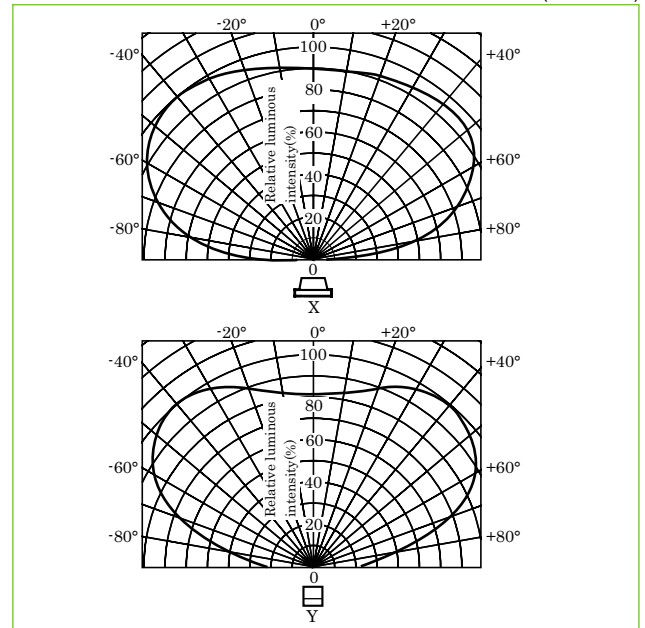
Outline Dimensions

(Unit : mm)



Directive Characteristics

(Ta=25 °C)



Absolute Maximum Ratings

(Ta=25 °C)

Model No.	Material	Power dissipation P (mW)	Forward current I _F (mA)	Peak forward current I _{FM} *1 (mA)	Derating factor (mA / °C)		Reverse voltage V _R (V)	Operating temperature T _{opr} (°C)	Storage temperature T _{stg} (°C)	Soldering temperature T _{sol} *2 (°C)
					DC	Pulse				
GM1J□35200AE series	AlGaInP on GaAs	52	20	40	0.27	0.53	5	-30 to +85	-40 to +100	350
GM1BC35370AC	InGaN	63	20	40	0.27	0.53	5	-20 to +80	-40 to +100	250
GM1GC35200AC	InGaN	60	15	35	0.20	0.47	5	-20 to +80	-40 to +100	250
GM1EG35200A	GaP	84	30	50	0.40	0.67	5	-30 to +85	-40 to +100	350

*1 Duty ratio=1/10, Pulse width=0.1 ms *2 For 3 s or less, Hand soldering.

Electro-optical Characteristics

(Ta=25 °C)

Resin type	Model No.	Emitting color	Forward voltage V _F (V)		Peak emission wavelength λ _p (nm) TYP.	Dominant wavelength λ _d (nm) TYP.	Luminous intensity I _v (mcd) TYP.	Spectrum radiation bandwidth Δλ (nm) TYP.	Reverse current		Terminal capacitance		Conditions I _F (mA)	Page for characteristics diagrams
			TYP.	MAX.					I _r (μA) MAX.	V _R (V)	C _t (pF) TYP.	(MHz)		
Colorless transparency	GM1JR35200AE	Red	2.0	2.6	638	630	13	15	100	4	60	1	5	54
	GM1JJ35200AE	Orange	2.0	2.6	627	618	19	15	100	4	60	1	5	
	GM1JS35200AE	Sunset orange	2.0	2.6	609	605	19	15	100	4	60	1	5	
	GM1JV35200AE	Amber	2.0	2.6	591	588	18.8	15	100	4	60	1	5	
	GM1JE35200AE	Yellow-green	2.0	2.6	575	572	13	15	100	4	60	1	5	
★ Milky diffusion	GM1BC35370AC	Blue	2.9	3.15	465	470	23	26	100	4	-	-	5	59
Colorless transparency	GM1GC35200AC	Green	3.7	4.1	518	525	54	36	100	4	-	-	10	59
Colorless transparency	GM1EG35200A	Yellow-green	2.1	2.8	567	-	19	30	10	4	35	1	20	69

★ Under development

(Notice)

- In the absence of confirmation by device specification sheets, SHARP takes no responsibility for any defects that may occur in equipment using any SHARP devices shown in catalogs, data books, etc.
- Contact SHARP in order to obtain the latest device specification sheets before using any SHARP device.
- Specifications are subject to change without notice for improvement.